

**Amendments to the Specification:**

Please replace the Abstract beginning at page 16, line 2, with the following rewritten paragraph:

--A wafer-cleaning module ~~is disclosed for removing~~ can remove contaminants from a semiconductor wafer prior to measurement in a metrology tool. ~~The cleaning module includes a~~ A heating chamber including a and heater plate of the cleaning module can be used to heat for heating the wafer by conduction, while a ~~while a~~ [[. A]] separate cooling chamber ~~is provided to~~ can be used to cool the wafer. The system is controlled by a processor so the heating cycle, cooling cycle and the time periods between these cycles and the measurement cycle are uniform for all wafers.--